

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:
Toshiyuki Nagase et al.

Application No.: 10/599,622

Confirmation No.: 1764

Filed: October 3, 2006

Art Unit: N/A

For: AI/AIN JOINT MATERIAL, BASE PLATE
FOR POWER MODULE, POWER MODULE,
AND MANUFACTURING METHOD OF
AI/AIN JOINT MATERIAL (AS AMENDED)

Examiner: Not Yet Assigned

SECOND PRELIMINARY AMENDMENT

MS Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

INTRODUCTORY COMMENTS

Prior to examination on the merits, please amend the above-identified U.S. patent application as follows:

Amendments to the Specification begin on page 2 of this paper.

Amendments to the Claims are reflected in the listing of claims which begins on page 3 of this paper.

Remarks/Arguments begin on page 8 of this paper.